NUF4220MN

Audio EMI Filter, 4 Line, with ESD Protection

NUF4220MN is a 4 line LC EMI filter array designed for audio applications. It offers greater than -30 dB attenuation at frequencies from 800 MHz to 5.0 GHz, with no line loss. This part is a single chip solution for audio interface applications, 2 speaker lines with a microphone line. This device also offers ESD protection-clamping transients from static discharges and ESD protection is provided across all capacitors.

Features

- Provides EMI Filtering and ESD Protection
- Integration of 20 Discretes
- Compliance with IEC61000–4–2 (Level 4) 18 kV (Contact)
- DFN8, 2x2 mm Package
- Moisture Sensitivity Level 1
- ESD Ratings: Machine Model = C Human Body Model = 3B
- Excellent Line Efficiency with Low Line Resistance $< 1.1 \Omega$ max
- This is a Pb-Free Device*

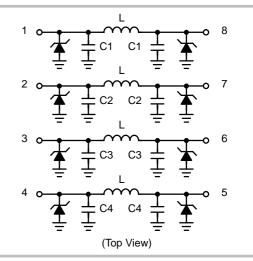
Applications

- Headset
- MP3s
- PDAs
- Digital Cameras
- Portable DVDs
- Handfree Interface



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MARKING DIAGRAM

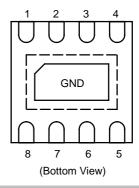


DFN8 CASE 506AA PLASTIC



R2 = Specific Device Code M = Date Code

■ = Pb-Free Package



ORDERING INFORMATION

Device	Package	Shipping [†]
NUF4220MNT1G	DFN8 (Pb-Free)	3000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

^{*}For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

NUF4220MN

MAXIMUM RATINGS

Parameter			Value	Unit
ESD Discharge IEC61000-4-2	Contact Discharge	V_{PP}	18	kV
Steady-State Power per Inductor		P_L	90	mW
Steady-State Power per Package		P _T	360	mW
Operating Temperature Range		T _{OP}	-40 to 85	°C
Storage Temperature Range		T _{stg}	-55 to 150	°C
Maximum Lead Temperature for Soldering Purposes (1.8 in from case for 10 s)			260	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

ELECTRICAL CHARACTERISTICS (T_J = 25°C unless otherwise noted)

Parameter	Test Conditions	Symbol	Min	Тур	Max	Unit
Maximum Reverse Working Voltage		V_{RWM}			5.0	V
Breakdown Voltage	I _R = 1.0 mA	V_{BR}	6.0	7.0	8.0	V
Leakage Current	V _{RWM} = 3.3 V	I _R			0.1	μΑ
Inductance		L		4.9		nΗ
Series Resistance		R _S	0.6	0.85	1.1	Ω
Capacitance (Note 1, 3)		C _d		205		pF
Cut-Off Frequency (Note 2)	Above this frequency, appreciable attenuation occurs	f _{3dB}		16		MHz

- Measured at 25°C, V_R = 0 V, f = 1.0 MHz.
 50 Ω source and 50 Ω load termination.
 Total line capacitance is 2 times the diode capacitance (C_d).

NUF4220MN

TYPICAL PERFORMANCE CURVES

(T_A = 25°C unless otherwise specified)

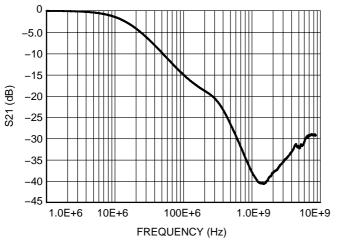


Figure 1. Typical Insertion Loss Characteristics

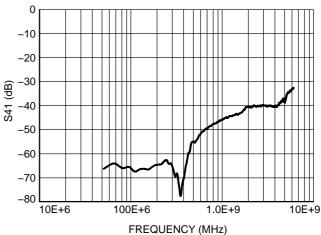


Figure 2. Typical Analog Crosstalk

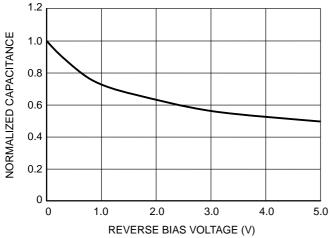


Figure 3. Typical Line Capacitance vs. Reverse Bias Voltage (Normalized to Capacitance @ 0 V)

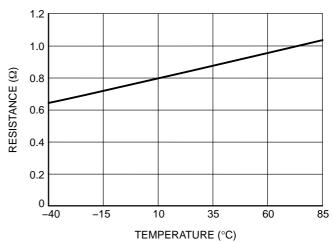


Figure 4. Typical Resistance Over Temperature

DIMENSIONING AND TOLERANCING PER

PAD AS WELL AS THE TERMINALS. MILLIMETERS

> 1.00 0.00 0.05

MIN MAX

0.20 REF

0.20 0.30

2 00 BSC

1.10 1.30

2.00 BSC

0.70 0.90 0.50 BSC

0.30 REF

0.35

0.10

0.25

0.80

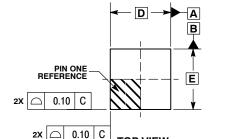
ASME Y14.5M, 1994 . CONTROLLING DIMENSION: MILLIMETERS. DIMENSION & APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.20 MM FROM TERMINAL TIP. COPLANARITY APPLIES TO THE EXPOSED



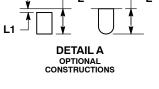


DFN8 2x2, 0.5P CASE 506AA **ISSUE F**

DATE 04 MAY 2016

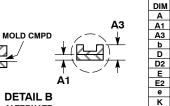




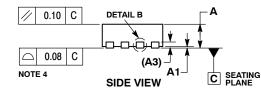


ALTERNATE CONSTRUCTIONS

EXPOSED Cu

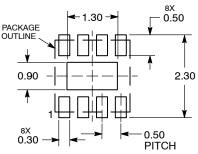


NOTES

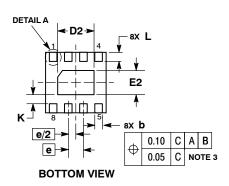


TOP VIEW

RECOMMENDED SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS



GENERIC MARKING DIAGRAM*



XX = Specific Device Code

= Date Code

= Pb-Free Device

*For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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DESCRIPTION:	DFN8, 2.0X2.0, 0.5MM PITCH		PAGE 1 OF 1	

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^{*}This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

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